Datasheet revision 1.0 www.chipquik.com

Thermoset Chip Glue - Dispense (Low) Viscosity (Red) - 30cc Syringe

Product Highlights

Heat curing epoxy adhesive designed to bond surface mount chips and ICs to printed circuit boards (PCBs). Low Viscosity. Designed to be dot/line dispensed.
Allows large/heavy surface mount components to be permanently bonded to a PCB during reflow, allowing two-sided surface mount reflow without larger chips/ICs coming loose.
Lead-Free / RoHS 3 Compliant / REACH Compliant

Specifications

Curing Time:	90 to 120 seconds at 150+ °C (302+ °F)
Recommended Curing Temperature:	150 to 260 °C (302 to 500 °F)
Maximum Curing Temperature:	260 °C (500 °F)
	Designed to cure at leaded and lead free reflow temperatures.
Operating Temperature Range:	-40 to 125 °C (-40 to 257 °F) (After Curing, After Reflow)
Lap Shear Strength (After Curing):	>15MPa (Steel-Steel, 25 °C (77 °F))
Packaging:	30cc/30g Syringe
Shelf Life:	Refrigerated >6 months, Unrefrigerated >6 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F), >4 hours @ 50-70% RH 22-28°C (72-82°F)

Application

Apply by dot dispensing, line dispensing, or with stencil and squeegee.

Cleaning

Clean using isopropyl alcohol (IPA).

Storage and Handling

Store at 3-25°C (37-77°F). Do not freeze. Allow 4 hours for thermoset chip glue to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

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